

A1
Amend

wherein the connecting conductor includes a plurality of layers formed of same material and at least one of the layers is formed as a stress-absorbing layer having lower hardness than other layer.

Sub B2
A2

7. (Amended) A semiconductor device comprising:
a semiconductor chip,
a protective insulating layer covering the surface of the semiconductor chip;
a plurality of connecting conductors connected to the surface of the semiconductor chip and penetrating the protective insulating layer [to] beyond the outside surface of the protective insulating layer;

wherein the connecting conductor includes a plurality of layers formed of different material and at least one of the layers is formed as a stress-absorbing layer having lower hardness than other layer.

REMARKS

Claims 1 through 13 are pending in this application. In response to the Office Action dated January 3, 2002, claims 1 and 7 have been amended to clarify that the plurality of connecting conductors extend beyond the outer surface of the protective insulating layer. Care has been exercised to avoid the introduction of new matter. Indeed, adequate descriptive support for the present Amendment should be apparent throughout the originally filed disclosure as, for example, the depicted embodiments and related discussion thereof commencing at page 4 of the written description of the specification,